

SG6516

PC Power Supply Supervisors

Features

- Two 12V Sense Input Pins: VS12 and VS12B
- Over-Voltage Protection (OVP) for 3.3V, 5V, and two 12V
- Over-Current Protection (OCP) for 3.3V, 5V, and two 12V
- Under-Voltage Protection (UVP) for 3.3V, 5V, and two 12V
- Open-Drain Output for PGO and FPO Pins
- 300ms Power-Good Delay
- 2.8ms PSON Control to FPO Turn-off Delay
- 48ms PSON Control Delay
- No Lock-up During the Fast AC Power On/Off
- Wide Supply Voltage Range: 4V to 15V

Applications

- Switch-Mode Power Supplies with Active PFC
- Servo System Power Supplies
- PC-ATX Power Supplies

Description


The SG6516 is designed to provide the supply voltage, current supervisor, remote on/off (PSON), power good (PGO) indicator, and fault protection (FPO) functions for switching power systems.

For supervisory functions, it provides the over-voltage protection (OVP) for 3.3V, 5V, and two 12V; over-current protection (OCP) for 3.3V, 5V, and two 12V; under-voltage protection (UVP) for 3.3V, 5V, and two 12V. When 3.3V, 5V, or 12V voltage decreases to 2.3V, 3.5V, and 9V, respectively, the under-voltage protection function is enabled. FPO is set HIGH to turn off the PWM controller IC. The voltage difference across external current shunt is used for OCP functions. An external resistor can be used to adjust the protection threshold. An additional protection input pin provides the flexibility for designing protection circuits.

The power supply is turned on after a 48ms delay when PSON signal is set from HIGH to LOW. To turn off the power supply, the PSON signal is set from LOW to HIGH with a delay of 48ms. The PGI circuitry provides a power-down warning signal for PGO. When PGI input is lower than the internal 1.25V reference voltage, the PGO signal is pulled LOW.

Ordering Information

Part Number	Operating Temperature Range	Package	Packing Method
SG6516DZ	-40°C to +85°C	16-pin Dual In-Line Package (DIP)	Rail
SG6516SZ	-40°C to +85°C	16-pin Small Outline Package (SOP)	Tape & Reel

 All packages are lead free per JEDEC: J-STD-020B standard.

Application Diagram

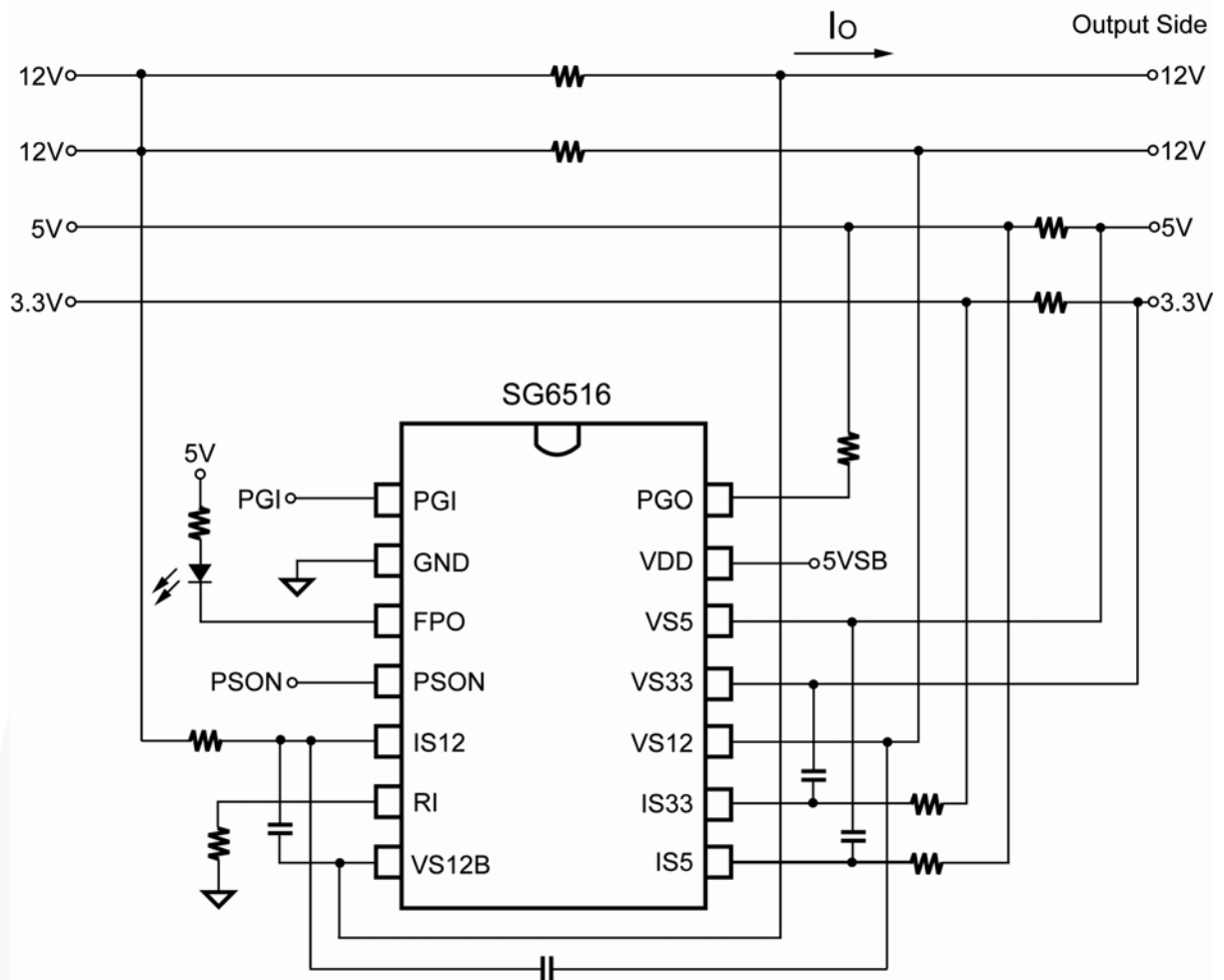


Figure 1. Typical Application

Block Diagram

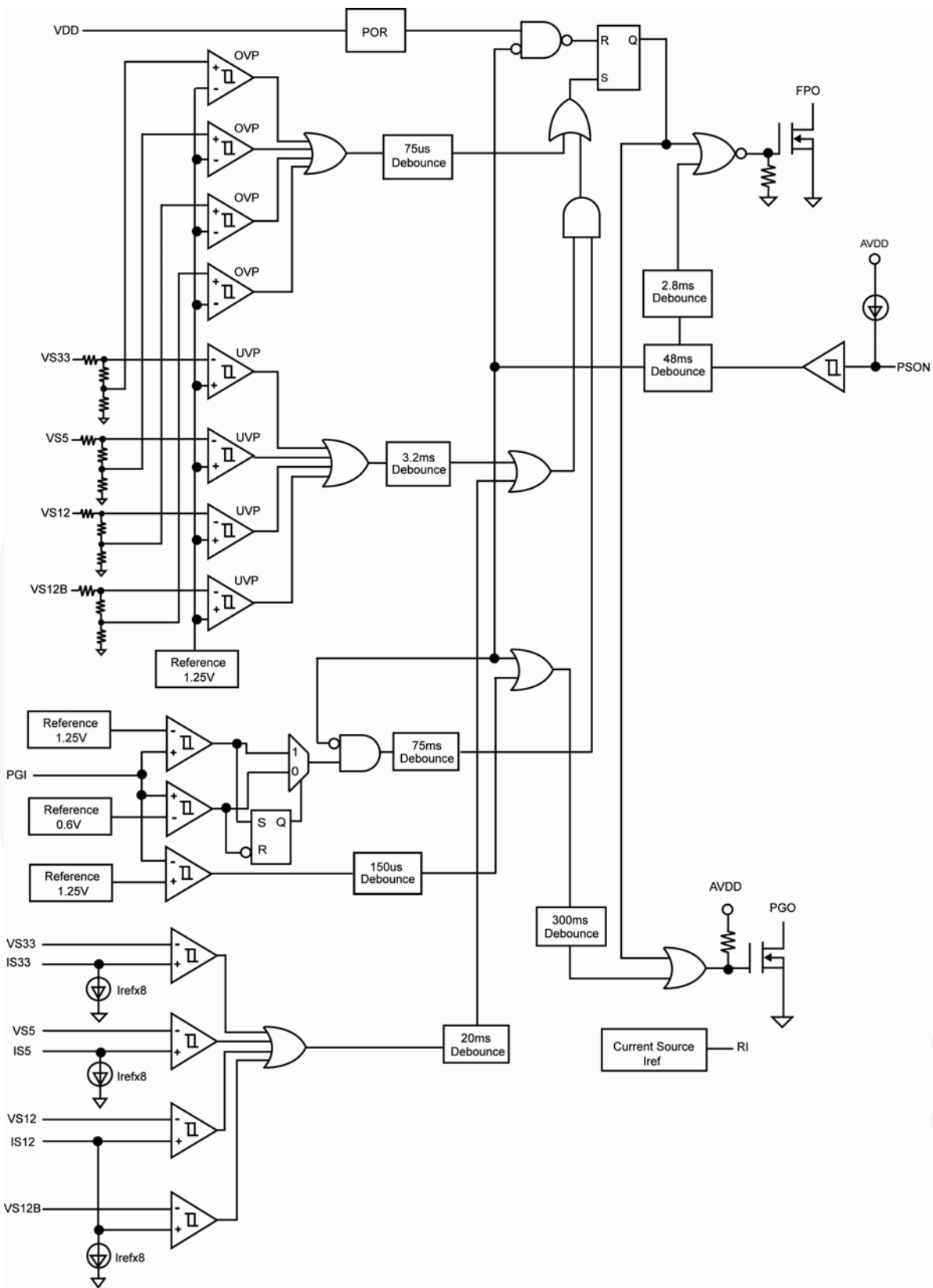


Figure 2. Function Block Diagram

Pin Configuration

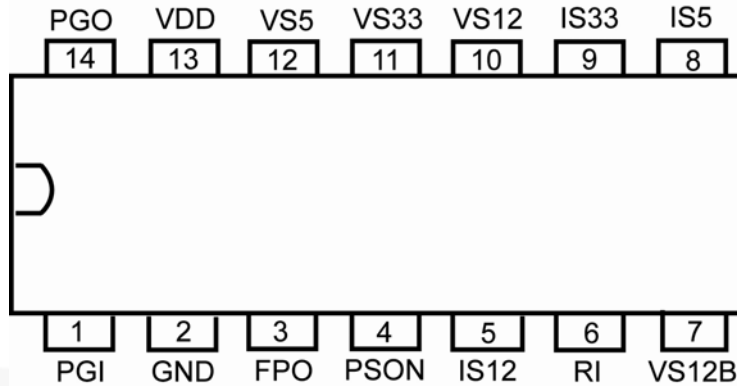


Figure 3. Pin Configuration(Top View)

Pin Definitions

Pin #	Name	Description
1	PGI	Power Good Input. For ATX SMPS, it detects AC line voltage through the main transformer.
2	GND	Ground.
3	FPO	Fault Protection Output. Output signal to control the primary PWM IC through an opto-coupler. When FPO is low, the PWM IC is enabled.
4	PSON	Remote on/off logic input from CPU or main board. The power supply is turned on/off after a 48ms delay.
5	IS12	12V over-current protection sense input. For typical applications, this pin is connected to the positive end of a current shunt through one resistor. When the voltage on IS12 is higher than that of VS12 by 5mV, OCP is enabled.
6	RI	Reference setting. One external resistor, R_i , connected between the RI and GND pins, determines a reference current, $I_{REF}=1.25/R_i$, for OCP programming.
7	VS12B	Second 12V over/under-voltage control sense input.
8	IS5	5V over-current protection sense input.
9	IS33	3.3V over-current protection sense input.
10	VS12	12V over/under-voltage control sense input.
11	VS33	3.3V over/under-voltage control sense input.
12	VS5	5V over/under-voltage control sense input.
13	VDD	Supply voltage: 4.2V ~ 15V. For ATX SMPS, it is connected to 5V-standby and 12V through diodes, respectively.
14	PGO	Power-Good logic Output, 0 or 1 (open-drain). Power good=1 means that the power supply is good for operation. The power-good delay is 300ms.

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only. All voltage values, except differential voltage, are given with respect to GND pin.

Symbol	Parameter		Min.	Max.	Unit
V _{DD}	DC Supply Voltage			16	V
V _{IN}	Input Voltage	PSON, PGI, VS5, IS5, VS33, IS33	-0.3	7.0	V
		VS12, VS12B, IS12	-0.3	15.0	V
V _{OUT}	Output Voltage	FPO, PGO	-0.3	8.0	V
T _J	Operating Junction Temperature		-40	+125	°C
T _{STG}	Storage Temperature Range		-55	+150	°C
T _L	Lead Temperature (Soldering)			+260	°C
ESD	Electrostatic Discharge Capability, Human Body Model			3.0	KV
	Electrostatic Discharge Capability, Machine Model			200	V

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter	Min.	Typ.	Max.	Unit
T _A	Operating Ambient Temperature	-40		+85	°C

Electrical Characteristics

$V_{DD}=5V$, $T_A=25^{\circ}C$, unless otherwise noted.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
V_{DD} Section						
V _{DD}	DC Supply Voltage		4.2		15.0	V
I _{DD1}	Supply Current 1	PSON=LOW		1.7	2.6	mA
I _{DD2}	Supply Current 2	PSON=HIGH		1.0	1.5	mA
t _R	Supply Voltage Rising Time		1			ms
V _{ST}	V _{DD} Start Threshold Voltage				4.2	V
Over-Voltage (OVP) and Over-Current (OCP) Protections						
V _{OVP}	Over-Voltage Protection	VS33	3.7	3.9	4.1	V
		VS5	5.7	6.1	6.5	
		VS12, VS12B	13.2	13.8	14.4	
I _{REF}	Ratio of Current-Sense Sink Current to Current-Sense Setting Pin (RI) Source Current	R _I =18.5kΩ ~ 75kΩ	7.6	8.0	8.4	
V _{OFFSET}	OCP Comparator Input Offset Voltage		-3		3	mV
I _{LKG-FPO}	Leakage Current (FPO)	FPO=5V			5	μA
V _{OL-FPO}	Low Level Output Voltage (FPO)	I _{SINK} 20mA			0.4	V
t _{OVP}	OVP Delay Time		33	75	110	μs
t _{OCP}	OCP Delay Time		12.5	20.0	27.5	ms
V _{RI}	RI Pin Voltage		0.98•Typ.	1.25	1.01•Typ.	V
I _{RI}	Output Current RI		12.5		62.5	μA
t _{ST-OCP}	Start-up OCP / UVP Protection Time	0.6V < PGI < 1.25V; FPO=Low	49	75	114	ms
Under-Voltage Protection and PGI, PGO						
V _{PGI_1}	Input Threshold Voltage	PGI 1	0.98•Typ.	1.25	1.02•Typ.	V
V _{PGI_2}	Input Threshold Voltage	PGI 2	0.96•Typ.	0.60	1.03•Typ.	V
V _{UVP}	Under-Voltage Protection	VS33	2.1	2.3	2.5	V
		VS5	3.3	3.5	3.7	
		VS12, VS12B	8.5	9.0	9.5	
t _{OND}	Under Voltage Turn-on Delay	PGI>0.6V	49	75	114	ms
t _{UVP}	UVP Delay	PGI>1.25V	2.4	3.2	4.0	ms
I _{LKG-PGO}	Leakage Current (PGO)	PGO=5V			5	μA
V _{OL-PGO}	Low Level Output Voltage (PGO)	V _{DD} =12V; I _{SINK} 10mA			0.4	V
t _{PG}	Timing PG Delay		200	300	450	ms
t _{ND1}	Noise Deglitch Time		90	150	210	μs
PSON Control						
I _{PSON}	Input Pull-up Current	PSON=0V		120		μA
V _{IH}	High-level Input Voltage		2			V
V _{IL}	Low-level Input Voltage				0.8	V
t _{PSON}	Timing PSON to On/Off	PSON LOW to FPO LOW	34	48	67	ms
		PSON HIGH to PGO LOW	34	48	67	
t _{PSOFF}	Timing PGO LOW to FPO HIGH		1.6	2.8	4.5	ms

Functional Description

The SG6516 provides over-current protection for the 3.3V, 5V, and two 12V rails. Whenever an OCP condition occurs at any of the voltage rails, PGO is LOW and FPO is open. The internal OCP comparators have a very small offset voltage ($\pm 3\text{mV}$). The sink currents of IS33, IS5, and IS12 are eight times the current at the RI pin. The current at the RI pin is V_{RI}/R_I .

The following example demonstrates how to set the over-current protection. If $I_1 \times R_1 > I_{RI} \times R_2$, OCP is active. If $R_1=5\text{m}\Omega$, $R_I=30\text{K}\Omega$, and the OCP active level is 35A; the R_2 resistor is:

$$R_2 = \frac{I_1 \times R_1}{I_{RI} \times 8} = 525\Omega \quad (1)$$

where C is bypass noise, with a suggested value between $1\mu\text{F} \sim 2.2\mu\text{F}$

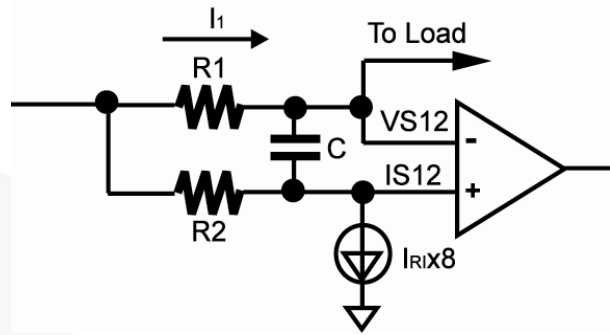


Figure 4. OCP Set-up

Timing Chart

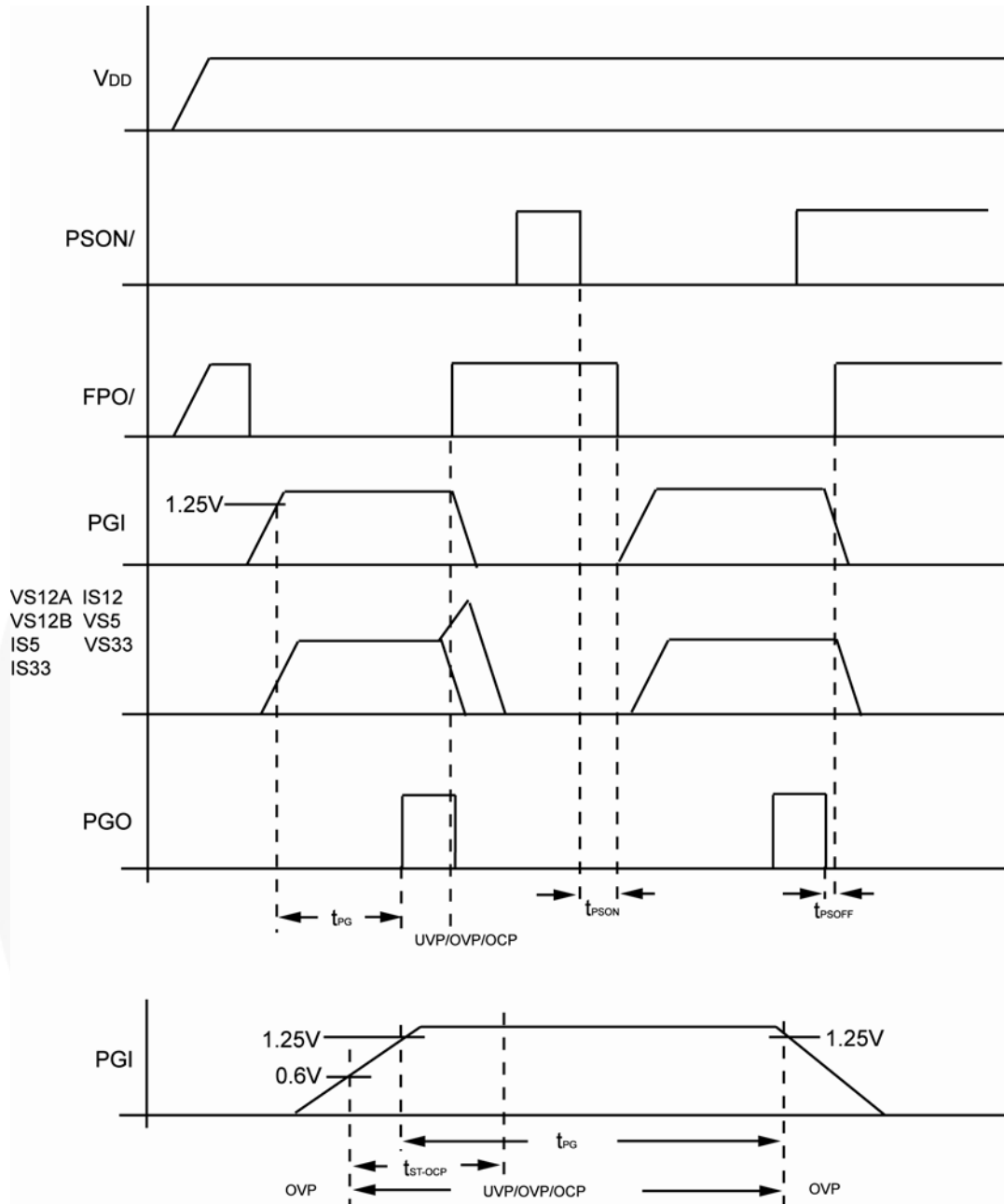


Figure 5. Timing Diagram

Typical Performance Characteristics

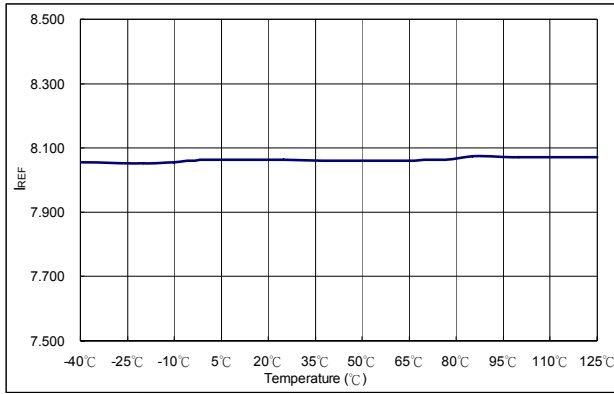


Figure 6. I_{REF} vs. T_A

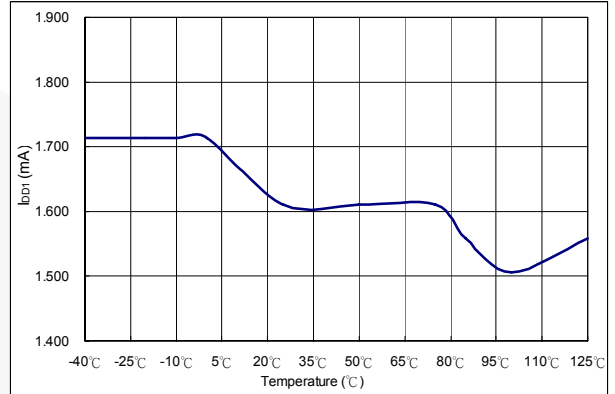


Figure 7. I_{D1} vs. T_A

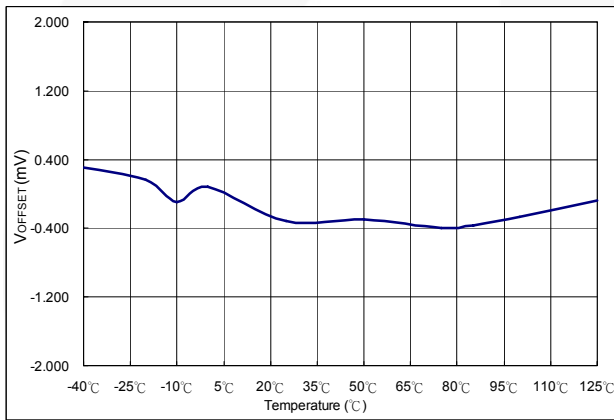


Figure 8. V_{OFFSET} vs. T_A

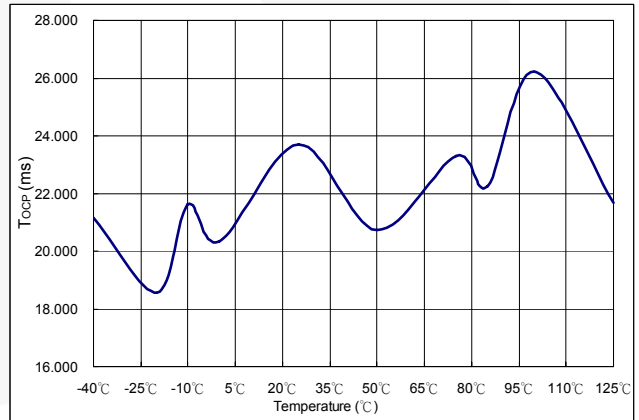


Figure 9. t_{OCP} vs. T_A

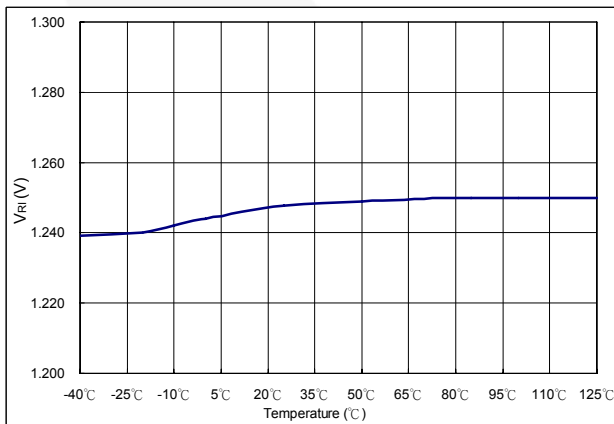


Figure 10. V_{RI} vs. T_A

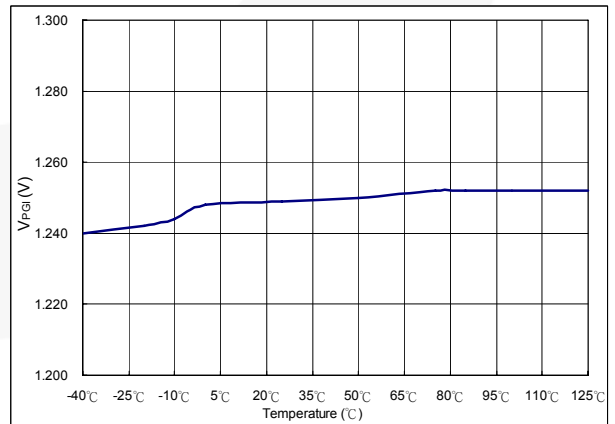


Figure 11. V_{PGI} vs. T_A

Physical Dimensions

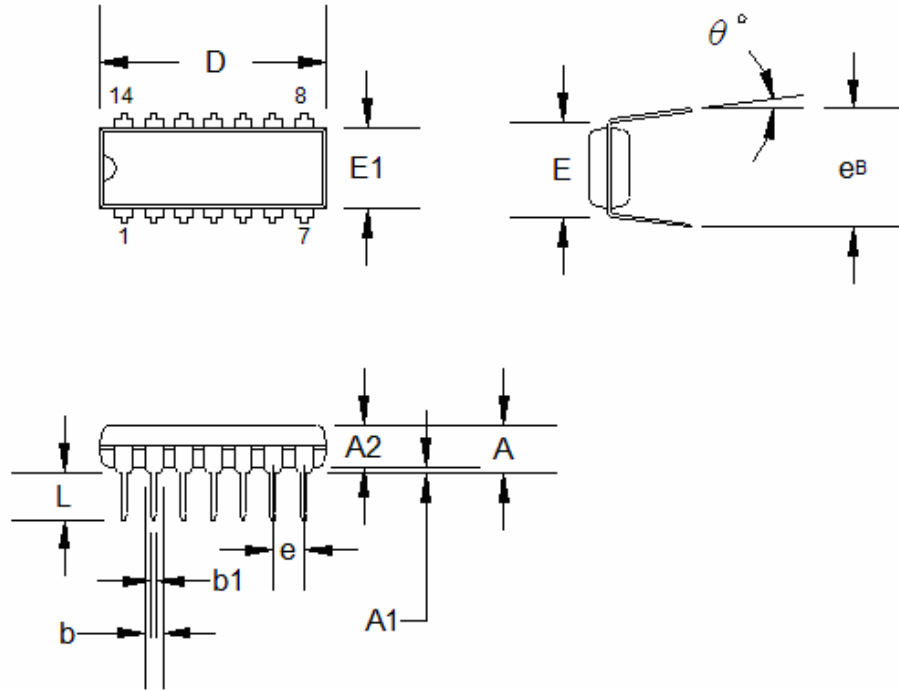


Figure 12. 14-PDIP

Symbol	Millimeter			Inch		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A			5.334			0.210
A1	0.381			0.015		
A2	3.175	3.302	3.429	0.125	0.130	0.135
b		1.524			0.060	
b1		0.457			0.018	
D	18.669	19.177	19.685	0.735	0.755	0.775
E		7.620			0.300	
E1	6.121	6.299	6.477	0.241	0.248	0.255
e		2.540			0.100	
L	2.921	3.302	3.810	0.115	0.130	0.150
e _B	8.509	9.017	9.525	0.335	0.355	0.375
θ°	0°	7°	15°	0°	7°	15°

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Physical Dimensions (Continued)

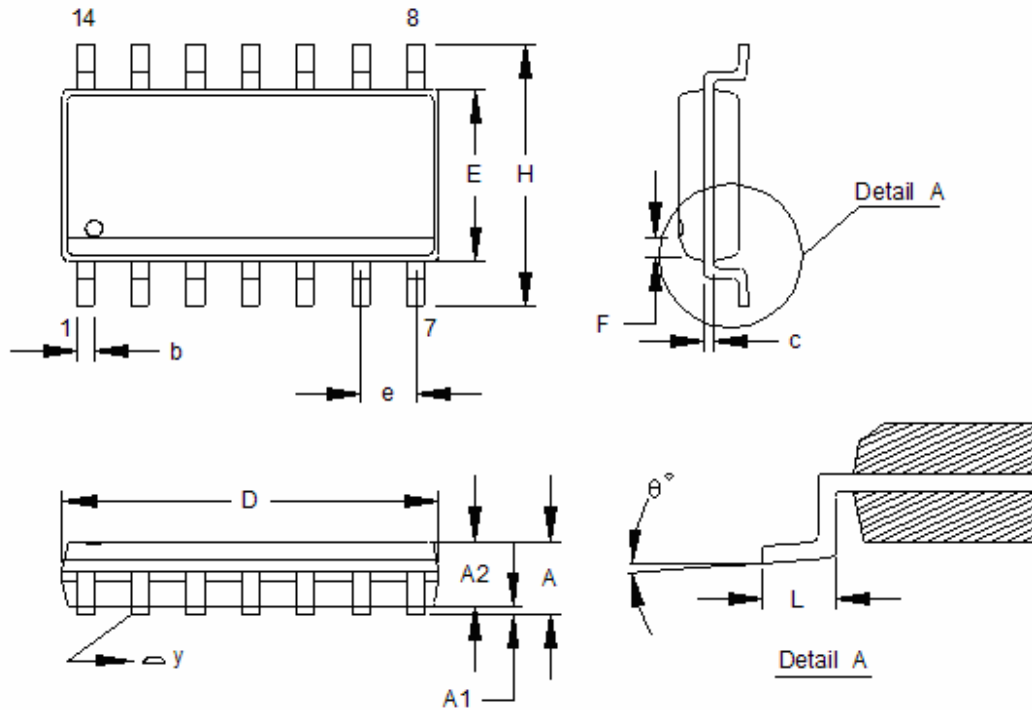


Figure 13. 14-SOIC

Symbol	Millimeter			Inch		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	1.346		1.753	0.053		0.069
A1	0.101		0.254	0.004		0.010
A2	1.244		1.499	0.049		0.059
b		0.406			0.016	
c		0.203			0.008	
D	9.804		10.008	0.386		0.394
E	3.810		3.988	0.150		0.157
e		1.270			0.050	
H	5.791		6.198	0.228		0.244
L	0.406		1.270	0.016		0.050
F		0.381X45°			0.015X45°	
y			0.101			0.004
θ°	0°		8°	0°		8°






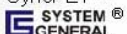
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